

## **APPENDIX C**

**(CLEAN VERSION OF ALL PENDING CLAIMS)**

**(Serial No. 09/942,183)**

## CLAIMS

What is claimed is:

1. A routing element for use in a semiconductor device assembly, comprising:  
a polymeric film; and  
at least one conductive trace including first and second portions carried adjacent opposite sides of  
said polymeric film, said at least one conductive trace located so as to facilitate electrical  
connection between remote first and second locations of the semiconductor device  
assembly.
2. The routing element of claim 1, further comprising:  
a contact pad located at each end of said at least one conductive trace.
3. (Amended) The routing element of claim 2, wherein said contact pads are located  
on opposite sides of said polymeric film from one another.
4. The routing element of claim 1, wherein said polymeric film is substantially  
planar.
5. The routing element of claim 1, wherein said polymeric film is flexible.
6. The routing element of claim 1, wherein said at least one conductive trace extends  
from a first location proximate a first edge of said polymeric film to a second location proximate  
an opposite, second edge of said polymeric film.
7. The routing element of claim 1, wherein said polymeric film carries a plurality of  
conductive traces.
8. The routing element of claim 1, wherein at least a portion of said at least one  
conductive trace is carried internally within said polymeric film.

9. The routing element of claim 1, wherein an electrically conductive via that extends at least partially through said polymeric film electrically connects said first and second portions.

10. A semiconductor device assembly comprising:  
a substrate;  
at least one semiconductor device secured to said substrate; and  
a polymeric film positioned at least partially over at least one of said substrate and said at least one semiconductor device, said polymeric film carrying at least one conductive trace in communication with at least one of a terminal of said substrate and a bond pad of said at least one semiconductor device.

11. The assembly of claim 10, wherein said polymeric film is at least partially superimposed over said at least one semiconductor device.

12. (Amended) The assembly of claim 11, wherein said at least one conductive trace at least partially establishes communication between said bond pad of said at least one semiconductor device and a corresponding terminal of said substrate.

13. The assembly of claim 12, wherein communication between said bond pad and said corresponding terminal is further established by at least one discrete conductive element positioned electrically between said at least one conductive trace and at least one of said bond pad and said corresponding terminal.

14. The assembly of claim 10, comprising a plurality of semiconductor devices at different locations on said substrate.

15. The assembly of claim 14, wherein said polymeric film is secured to said substrate laterally between at least two semiconductor devices of said plurality of semiconductor devices.

16. (Amended) The assembly of claim 15, wherein at least one conductive trace carried by said polymeric film at least partially establishes communication between a bond pad of one of said at least two semiconductor devices and a corresponding bond pad of another of said at least two semiconductor devices.

17. The assembly of claim 16, wherein said at least one conductive trace communicates with a terminal of said substrate which, in turn, communicates with said bond pad.

18. The assembly of claim 17, further comprising discrete conductive elements between said terminal and each of said at least one conductive trace and said bond pad.

19. The assembly of claim 10, wherein said substrate comprises at most four conductive layers.

20. (Amended) The assembly of claim 10, wherein said at least one conductive trace provides a more direct electrical route than any conductive trace carried by said substrate.

21. (Amended) The assembly of claim 16, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace carried by said polymeric film.

22. The assembly of claim 10, wherein said polymeric film and said at least one conductive trace extend through a plane of said substrate.

23. The assembly of claim 22, wherein opposite ends of said at least one conductive trace are electrically exposed at opposite sides of said polymeric film.

24. The assembly of claim 22, wherein opposite ends of said at least one conductive trace are electrically exposed at the same side of said polymeric film.

25. A carrier for at least one semiconductor device, comprising:  
a substrate carrying at least one terminal and at least one conductive trace; and  
a polymeric film positioned at least partially over said substrate and carrying at least one additional conductive trace.

26. The carrier of claim 25, wherein said substrate comprises at most four conductive layers.

27. The carrier of claim 25, wherein said polymeric film is at least partially adhered to said substrate.

28. The carrier of claim 27, wherein said at least one additional conductive trace at least partially establishes communication between said at least one terminal and another terminal carried upon said substrate.

29. (Amended) The carrier of claim 28, wherein communication between said at least one terminal and said another terminal is further established by way of at least one discrete conductive element that electrically connects said at least one additional conductive trace to at least one of said at least one terminal and said another terminal.

30. The carrier of claim 25, wherein said polymeric film is configured to be disposed at least partially over the at least one semiconductor device carried by said substrate.

31. The carrier of claim 25, wherein said at least one additional conductive trace carried upon said polymeric film is configured to at least partially establish communication between said at least one terminal and a corresponding bond pad of the at least one semiconductor device.

32. The carrier of claim 31, wherein communication between said at least one terminal and said corresponding bond pad is further established by way of at least one discrete conductive element electrically connecting said at least one additional conductive trace to at least one of said at least one terminal and said corresponding bond pad.

33. The carrier of claim 31, wherein said at least one additional conductive trace carried upon said polymeric film is configured to at least partially establish communication between a bond pad of the at least one semiconductor device and a corresponding bond pad of at least another semiconductor device carried by said substrate.

34. The carrier of claim 33, wherein communication between said bond pad and said corresponding bond pad is further established by way of at least one discrete conductive element electrically connecting said at least one additional conductive trace and at least one of said bond pad and said corresponding bond pad.

35. The carrier of claim 25, wherein said substrate includes at least one aperture formed therethrough for receiving a portion of said polymeric film and said at least one additional conductive trace to facilitate positioning of different portions of said polymeric film over portions of opposite sides of said substrate.

36. The carrier of claim 35, wherein opposite ends of said at least one additional conductive trace are electrically exposed at opposite sides of said polymeric film.

37. The carrier of claim 35, wherein opposite ends of said at least one additional conductive trace are electrically exposed at the same side of said polymeric film.

59. A semiconductor device assembly comprising:  
a substrate carrying a first plurality of conductive traces;  
a routing element carrying a second plurality of conductive traces positioned at least partially on  
said substrate; and  
at least one semiconductor device secured to said substrate.

60. The assembly of claim 59, wherein said routing element is at least partially  
superimposed over said at least one semiconductor device.

61. The assembly of claim 60, wherein at least one conductive trace of said second  
plurality of conductive traces at least partially establishes electrical communication between a  
bond pad of said at least one semiconductor device and a corresponding terminal of said  
substrate.

62. The assembly of claim 61, wherein communication between said bond pad and  
said corresponding terminal is further established by at least one discrete conductive element  
positioned electrically between said at least one conductive trace and at least one of said bond  
pad and said corresponding terminal.

63. The assembly of claim 59, comprising a plurality of semiconductor devices at  
different locations on said substrate.

64. The assembly of claim 63, wherein said routing element is secured to said  
substrate laterally between at least two semiconductor devices of said plurality of semiconductor  
devices.

65. The assembly of claim 64, wherein at least one conductive trace of said second plurality of conductive traces at least partially establishes communication between a bond pad of one of said at least two semiconductor devices and a corresponding bond pad of another of said at least two semiconductor devices.

66. The assembly of claim 65, wherein said at least one conductive trace communicates with a terminal of said substrate which, in turn, communicates with said bond pad.

67. The assembly of claim 66, further comprising discrete conductive elements between said terminal and each of said at least one conductive trace and said bond pad.

68. The assembly of claim 59, wherein said substrate comprises at most four conductive layers.

69. (Amended) The assembly of claim 59, wherein said second plurality of conductive traces of said routing element provide a more direct electrical route than any conductive trace carried by said substrate.

70. (Amended) The assembly of claim 65, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace of said second plurality of conductive traces.

71. (Amended) The assembly of claim 59, wherein said routing element and said second plurality of conductive traces extends through a plane of said substrate.

72. (Amended) The assembly of claim 71, wherein opposite ends of at least one conductive trace of said second plurality of conductive traces are electrically exposed at opposite sides of said routing element.



73. (Amended) The assembly of claim 71, wherein opposite ends of at least one conductive trace of said second plurality of conductive traces are electrically exposed at the same side of said routing element.